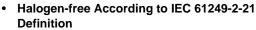


P-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}$ (Ω) Max.	I _D (A)	Q _g (Typ.)		
- 100	$0.167 \text{ at V}_{GS} = -10 \text{ V}$	- 18	37		
	$0.180 \text{at V}_{GS} = -4.5 \text{V}$	- 14	01		

FEATURES

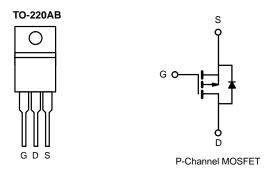




- TrenchFET[®] Power MOSFET
- 100 % R_q and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Power Switch
- Load Switch in High Current Applications
- DC/DC Converters



ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
Parameter			Limit	Unit		
Drain-Source Voltage		V _{DS}	- 100	V		
Gate-Source Voltage	V _{GS}	± 20	V			
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 25 °C	I-	- 18	Δ.		
Continuous Diam Current (1) = 150°C)	T _C = 70 °C	- I _D	- 13			
Pulsed Drain Current (t = 300 μs)	I _{DM}	- 100	A			
Avalanche Current		I _{AS}			- 10	
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	31	mJ		
Mariana Barra Biantania	T _C = 25 °C	В	11.7 ^b	W		
Maximum Power Dissipation ^a	T _A = 25 °C ^c	– P _D	1.1			
Operating Junction and Storage Temperature R	ange	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Limit	Unit			
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	60	°CAM			
Junction-to-Case (Drain)	R _{thJC}	9	°C/W			

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).

1



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 100			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 2.5		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 100 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μΑ	
		V _{DS} = - 100 V, V _{GS} = 0 V, T _J = 150 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 18			Α	
	D	V _{GS} = - 10 V, I _D = - 14 A		0.167		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 12 A		0.180			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 20 V, I _D = - 14 A		20		S	
Dynamic ^b							
Input Capacitance	C _{iss}			1765		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 20 V, f = 1 MHz		330			
Reverse Transfer Capacitance	C _{rss}]		280			
Total Gate Charge ^c	Q_g			67	100		
Gate-Source Charge ^c	Q_{gs}	V _{DS} = - 20 V, V _{GS} = - 10 V, I _D = - 14 A		13.5		nC	
Gate-Drain Charge ^c	Q_{gd}]		14			
Gate Resistance	R_g	f = 1 MHz	0.5	2.5	5	Ω	
Turn-On Delay Time ^c	t _{d(on)}			10	20		
Rise Time ^c	t _r	V_{DD} = - 20 V, R_L = 2 Ω		11	20		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 10 A, $V_{GEN} =$ - 10 V, $R_g =$ 1 Ω		42	63	ns ns	
Fall Time ^c	t _f]		12	20		
Drain-Source Body Diode Ratings ar	nd Characteri	stics T _C = 25 °C ^b					
Continuous Current	Is	.			- 18		
Pulsed Current	I _{SM}				- 100	Α	
Forward Voltage ^a	V _{SD}	I _F = - 10 A, V _{GS} = 0 V		- 0.8	- 1.5	V	
Reverse Recovery Time	t _{rr}			38	57	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 10 A, dI/dt = 100 A/μs		2.3	3.5	Α	
Reverse Recovery Charge	Q _{rr}			40	60	nC	

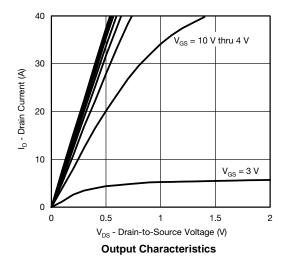
Notes:

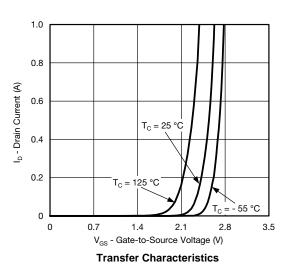
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$ b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

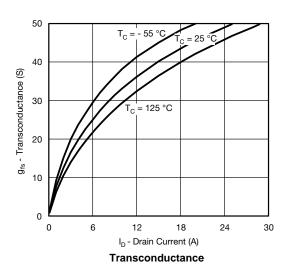
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

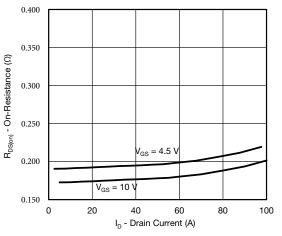


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

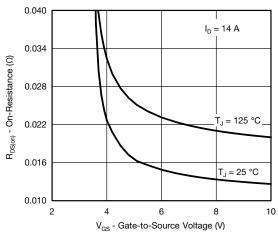




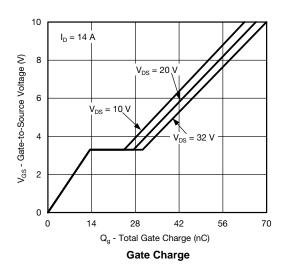




On-Resistance vs. Drain Current

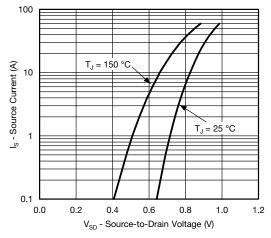


On-Resistance vs. Gate-to-Source Voltage

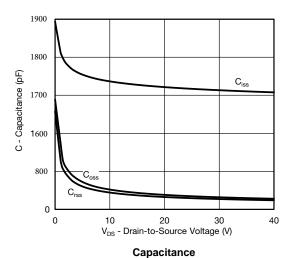




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Source-Drain Diode Forward Voltage



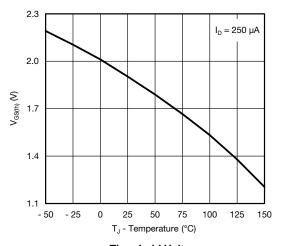
1.9 V_{GS} = 10 V V_{GS} = 4.5 V

 $$T_{\rm J}$$ - Junction Temperature (°C) **On-Resistance vs. Junction Temperature**

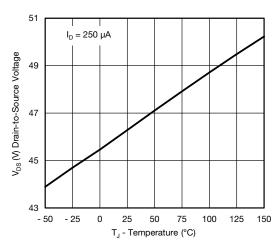
50

100

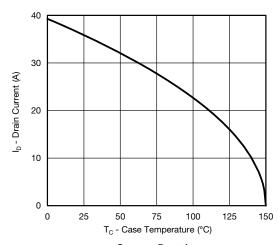
125



Threshold Voltage



Drain Source Breakdown vs. Junction Temperature



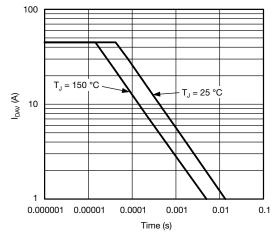
Current Derating

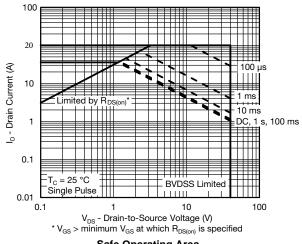
2.2

- 50



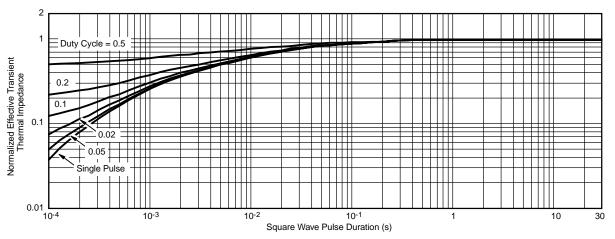
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Single Pulse Avalanche Current Capability vs. Time

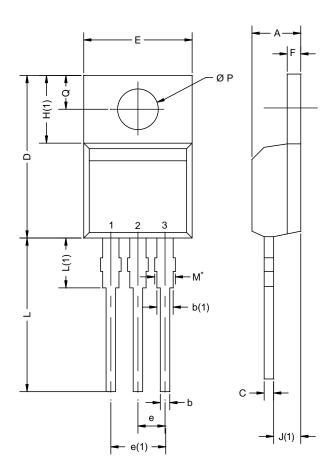




Normalized Thermal Transient Impedance, Junction-to-Case



TO-220AB



	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
E	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471					

Notes

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM

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